

INVENTORSHIP DECLARATION

I HEREBY DECLARE THAT:

My residence, mailing address, and citizenship are stated next to my name in PART A hereof.

I believe I am the original and sole inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled

METHODS OF THINNING A SILICON WAFER USING HF AND OZONE

the specification of which:

- is attached hereto.
- was filed on _____ as Application Serial No. _____ and was amended on _____ (if applicable).

I have reviewed and understand the contents of the above-identified specification, including the claims, as amended by any amendment referred to above.

I acknowledge the duty to disclose information which is material to the examination of this application in accordance with 37 CFR §1.56, including, for continuation-in-part applications, material information which became available between the filing date of the prior application and the national or PCT international filing date of the continuation-in-part application.

I hereby claim priority benefits under 35 USC §119(a)-(d) or (f), §172, or §365(a)-(b) of any foreign or international application(s) for patent or inventor's certificate listed in PART B hereof and have also identified in PART B hereof any such foreign or international application having a filing date before that of the application of which priority is claimed.

I hereby declare that all statements made herein of my knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon. I understand that the execution of this document does not in itself establish an attorney-client relationship between the undersigned and Perkins Coie, LLP, or any of its attorneys.

See page 2 attached, signed, and made a part hereof.

INVENTORSHIP DECLARATION

PART A: INVENTOR INFORMATION AND SIGNATURE

Full name of FIRST inventor: Eric J. Bergman

Citizenship: U.S.

Mailing Address: 2355 Whitefish Stage Road
Kalispell, Montana 59901

Residence (if different): _____

Inventor's Signature: E. J. Bergman

Date: Jul 10, 2003

INVENTORSHIP DECLARATION

**PART B: CLAIM TO PRIORITY OF FOREIGN APPLICATION(S) UNDER 35 U.S.C. 119(a-d)
and (f) §172, or §365(a)-(b)**

Country	App. No.	Filing Date	Priority Not Claimed
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PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Eric J. BERGMAN

FILED: Concurrently Herewith

FOR: **METHODS OF THINNING A SILICON
WAFER USING HF AND OZONE**

Power of Attorney by Assignee and Certification
Under 37 CFR §3.73(b)

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

I, the undersigned, acting on behalf of the Assignee of the entire right, title and interest in the above-identified patent application, by virtue of an Assignment filed concurrently herewith appoint the attorneys and agents listed below to prosecute this application and transact all business with the U.S. Patent and Trademark Office in connection therewith. This appointment is to the exclusion of the inventor(s) and their attorney(s) and agent(s) in accordance with the provisions of 37 CFR 3.71.

All prior powers of attorney for this application are hereby revoked. The Assignee hereby appoints STEPHEN E. ARNETT, Registration No. 47,392; RODGER K. CARREYN, Registration No. 50,774; BRIAN R. COLEMAN, Registration No. 39,145; CHRISTOPHER DALEY-WATSON, Registration No. 34,807; PETER J. DEHLINGER, Registration No. 28,006; DAVID BOGART DORT, Registration No. 50,213; DAVID T. DUTCHER, Registration No. 51,638; LEEANN GORTHEY, Registration No. 37,337; JOSEPH HAMILTON, Registration No. 51,770; PAUL L. HICKMAN, Registration No. 28,516; EDWARD S. HOTCHKISS, Registration No. 33,904; KAREN Y. HUI, Registration No. 44,785; STEVEN KELLEY, Registration No. 43,449; TAMIZ KHAN, Registration No. 46,273; JONATHAN P. KUDLA, Registration No. 47,724; STEVEN D. LAWRENZ, Registration No. 37,376; KATHERINE D. LEE, Registration No. 44,865; JACQUELINE F. MAHONEY, Registration No. 48,390; JUDY M. MOHR, Registration No. 38,563; CHUN NG, Registration No. 36,878; NGUYEN H. NGUYEN, Registration No. 43,834; REBEKKA C. NOLL, Registration No. 46,962; KENNETH H. OHRINGER, Registration No. 31,646; PAUL T. PARKER, Registration No. 38,264; MAURICE J. PIRIO, Registration No. 33,273; TIM R. SEELEY, Registration No. 53,575; LAUREN

SLIGER, Registration No. 51,086; CARINA M. TAN, Registration No. 45,769; MARK A. THOMAS, Registration No. 37,953; LARRY W. THROWER, Registration No. 47,994; JOHN M. WECHKIN, Registration No. 42,216; JAMES A.D. WHITE, Registration No. 43,985; MICHAEL J. WISE, Registration No. 34,047; ROBERT G. WOOLSTON, Registration No. 37,263; and JAMES J. ZHU, Registration No. 52,396; all affiliated with Perkins Coie LLP, and HARRY M. CROSS, JR., Registration No. 22,229.

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In accordance with 37 CFR 3.73(b), I hereby certify that I am empowered to act on behalf of the Assignee. To the best of my knowledge and belief, title is in the Assignee, as evidenced by the Assignment noted above.

I further declare that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Title 18, USC §1001 and that such willful false statements may jeopardize the validity of this application or any patent resulting therefrom.

ASSIGNEE: Semitool, Inc.

Signature: Larry A. Viano

Typed Name: Larry A. Viano

Title: Secretary and CFO

Date: 7-11-3

Address: 655 West Reserve Drive, Kalispell, MT 59901